



Material Content Data Sheet



Sales Product Name		ICL8201		Issued		20. July 2018			
MA#		MA001303674							
Package		PG-SOT23-6-1		Weight*		18.67 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.361	1.93	1.93	19341	19341	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		117		
	non noble metal	zinc	7440-66-6	0.009	0.05		468		
	non noble metal	iron	7439-89-6	0.175	0.94		9363		
wire	non noble metal	copper	7440-50-8	7.097	38.02	39.02	380162	390110	
	noble metal	gold	7440-57-5	0.227	1.22	1.22	12176	12176	
	encapsulation	organic material	carbon black	1333-86-4	0.020	0.11		1067	
plating	plastics	epoxy resin	-	1.523	8.16		81612		
	inorganic material	silicondioxide	60676-86-0	8.414	45.06	53.33	450730	533409	
	non noble metal	tin	7440-31-5	0.465	2.49	2.49	24899	24899	
glue	noble metal	silver	7440-22-4	0.167	0.90	0.90	8950	8950	
*deviation	< 10%	plastics	acrylic resin	-	0.046	0.24		2445	
		noble metal	silver	7440-22-4	0.162	0.87	1.11	8670	11115
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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